GUIDE RAIL MATERIAL: COPPER ALLOY
GUIDE RAIL FINISH: 0.4 MICROMETERS MIN THK TIN COATING

EMI GASKET MATERIAL: COPPER ALLOY
EMI GASKET PLATING: 2 MICROMETERS MIN THK TIN PLATE

DATUMS X AND Y AND BSC DIMENSIONS TO BE
ESTABLISHED BY CUSTOMER

4. DESIGN ACCEPTS MODULES THAT ARE COMPLIANT
WITH X2 SPECIFICATION REV 2.0b

SEE CUSTOMER DRAWING 1367337-1 FOR
CONNECTION PAD DIMENSIONS

RECOMMENDATION FOR P.C. BOARD HOLES:
COPPER UNDERPLATE, 25-50 MICROMETERS THICK,
FOLLOWED BY ANY OF THESE SURFACE FINISHES:

A. HASL SnPb: 35 MICROMETERS WAX THK

B. GALVANIC Ag: 4-5 MICROMETERS Ni + 0.1-0.5
MICROMETERS Au

C. OSP: 0.2-0.5 MICROMETERS THK

D. IMMERSION Sn: 0.5 MICROMETERS MIN THK

E. IMMERSION Au: 4-5 MICROMETERS Ni + 0.1-0.5
MICROMETERS Au

F. IMMERSION Ag: 0.1-0.3 MICROMETERS

7. BARE EDGES PERMITTED

8. BEZEL REQUIREMENTS PER X2 MSA

9. REFER TO INSTRUCTION SHEET 408-8997 FOR
ADDITIONAL INFORMATION.
CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEPOUT (EXCEPT CHASSIS GROUND)

THIS AREA DENOTES COMPONENT KEPOUT (TRACES ALLOWED)

SURFACE OF TOP BOARD

RECOMMENDED P.C. BOARD LAYOUT